# Field Effect Transistor -N-Channel, Enhancement Mode

# 2N7002DW

## Features

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25°C unless otherwise noted)							
Symbol	Parameter	Ratings	Units				
V <sub>DSS</sub>	Drain-Source Voltage		60	V			
V <sub>DGR</sub>	Drain-Gate Voltage (R <sub>GS</sub>	≤ 1.0 MΩ)	60	V			
V <sub>GSS</sub>	Gate-Source Voltage	Gate-Source Voltage Continuous		V			
		Pulsed	±40				
I <sub>D</sub>	Drain Current	n Current Continuous Continuous at 100°C		mA			
		Pulsed	800				
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range		-55 to +150	°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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SC-88/SC70-6/SOT-363 CASE 419B-02

# MARKING DIAGRAM



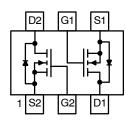
= Specific Device Code

2N

Μ

= Assembly Operation Month

# **PIN CONNECTIONS**



# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

# **THERMAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
PD	Total Device Dissipation	200	mW
	Derate Above $T_A = 25^{\circ}C$	1.6	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	415	°C/W

1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. Minimum land pad size.

# 2N7002DW

## **ORDERING INFORMATION**

Part Number	Top Mark	Package	Shipping <sup>†</sup>
2N7002DW	2N	SC70–6 (Pb–Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
F CHARAC	TERISTICS (Note 2)			-		-
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 10 $\mu$ A	60	78	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$	-	0.001	1.0	μA
		$V_{DS}$ = 60 V, $V_{GS}$ = 0 V, $T_J$ = 125 $^\circ C$	-	7	500	
I <sub>GSS</sub>	Gate-Body Leakage	$V_{GS}=\pm 20~V,~V_{DS}=0~V$	-	0.2	±10	nA
I CHARACT	ERISTICS (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1.00	1.76	2.0	V
R <sub>DS(on)</sub>	Static Drain–Source	$V_{GS}$ = 5 V, I <sub>D</sub> = 0.05 A	-	1.6	7.5	Ω
	On-Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 0.5 A	-		2.0	
		$V_{GS}$ = 10 V, $I_D$ = 0.5 A, $T_J$ = 125 $^\circ C$	-	2.53	13.5	
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS}$ = 10 V, $V_{DS}$ = 7.5 V	0.50	1.43	-	Α
9fs	Forward Transconductance	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.2 \text{ A}$	80.0	356.5	-	mS
NAMIC CH	ARACTERISTICS		•			
C	Input Consoitance	$V_{-2} = 25 V V_{-2} = 0 V f = 1.0 M H_{-2}$		27.0	50	۳E

C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 25 V, $V_{GS}$ = 0 V, f = 1.0 MHz	-	37.8	50	pF
C <sub>oss</sub>	Output Capacitance		-	12.4	25	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	6.5	7	pF

### SWITCHING CHARACTERISTICS (Note 2)

t <sub>D(ON)</sub>	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_D = 0.2 \text{ A}, V_{GEN} = 10 \text{ V},$	-	5.85	20	ns
t <sub>D(OFF)</sub>	Turn-Off Delay Time	R <sub>L</sub> = 150 Ω, R <sub>GEN</sub> = 25 Ω	-	12.5	20	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Short duration test pulse used to minimize self-heating effect.

# **TYPICAL PERFORMANCE CHARACTERISTICS**

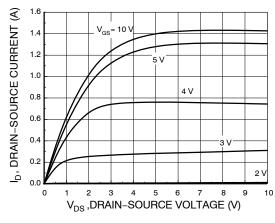
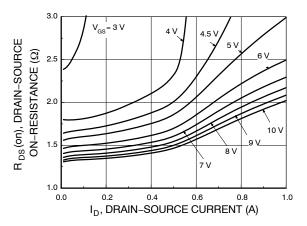
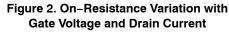


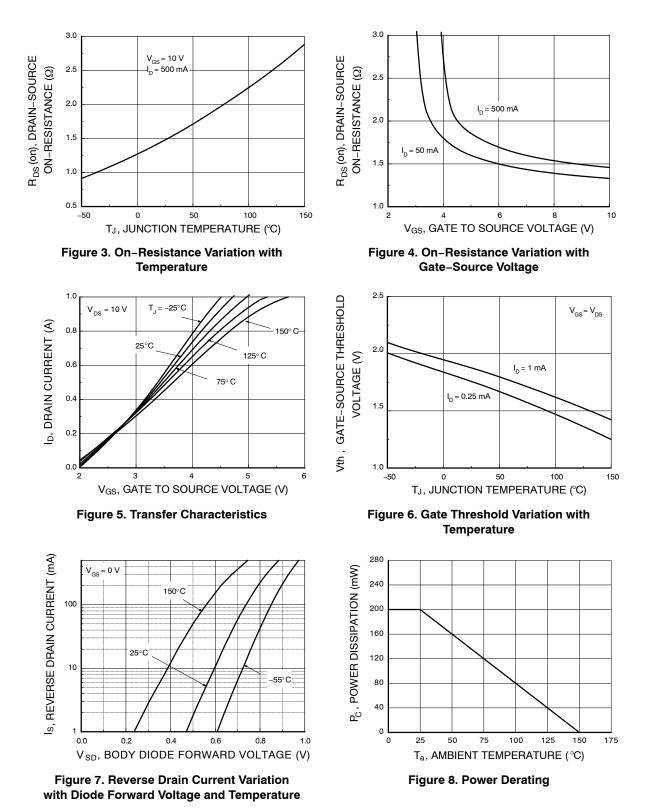
Figure 1. On–Region Characteristics





# 2N7002DW

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)



0.043

0.004





- XXX = Specific Device Code

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering

details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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#### SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE Y

## DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13:	STYLE 14:	STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:
PIN 1. ANODE	PIN 1. VREF	PIN 1. ANODE 1	PIN 1. BASE 1	PIN 1. BASE 1	PIN 1. VIN1
2. N/C	2. GND	2. ANODE 2	2. EMITTER 2	2. EMITTER 1	2. VCC
3. COLLECTOR	3. GND	3. ANODE 3	3. COLLECTOR 2	3. COLLECTOR 2	3. VOUT2
4. EMITTER	4. IOUT	4. CATHODE 3	4. BASE 2	4. BASE 2	4. VIN2
5. BASE	5. VEN	5. CATHODE 2	5. EMITTER 1	5. EMITTER 2	5. GND
6. CATHODE	6. VCC	6. CATHODE 1	6. COLLECTOR 1	6. COLLECTOR 1	6. VOUT1
STYLE 19:	STYLE 20:	STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:
PIN 1. I OUT	PIN 1. COLLECTOR	PIN 1. ANODE 1	PIN 1. D1 (i)	PIN 1. Vn	PIN 1. CATHODE
2. GND	2. COLLECTOR	2. N/C	2. GND	2. CH1	2. ANODE
3. GND	3. BASE	3. ANODE 2	3. D2 (i)	3. Vp	3. CATHODE
4. V CC	4. EMITTER	4. CATHODE 2	4. D2 (c)	4. N/C	4. CATHODE
5. V EN	5. COLLECTOR	5. N/C	5. VBUS	5. CH2	5. CATHODE
6. V REF	6. COLLECTOR	6. CATHODE 1	6. D1 (c)	6. N/C	6. CATHODE
STYLE 25:	STYLE 26:	STYLE 27:	STYLE 28:	STYLE 29:	STYLE 30:
PIN 1. BASE 1	PIN 1. SOURCE 1	PIN 1. BASE 2	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. SOURCE 1
2. CATHODE	2. GATE 1	2. BASE 1	2. DRAIN	2. ANODE	2. DRAIN 2
3. COLLECTOR 2	3. DRAIN 2	3. COLLECTOR 1	3. GATE	3. COLLECTOR	3. DRAIN 2
4. BASE 2	4. SOURCE 2	4. EMITTER 1	4. SOURCE	4. EMITTER	4. SOURCE 2
5. EMITTER	5. GATE 2	5. EMITTER 2	5. DRAIN	5. BASE/ANODE	5. GATE 1
6. COLLECTOR 1	6. DRAIN 1	6. COLLECTOR 2	6. DRAIN	6. CATHODE	6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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